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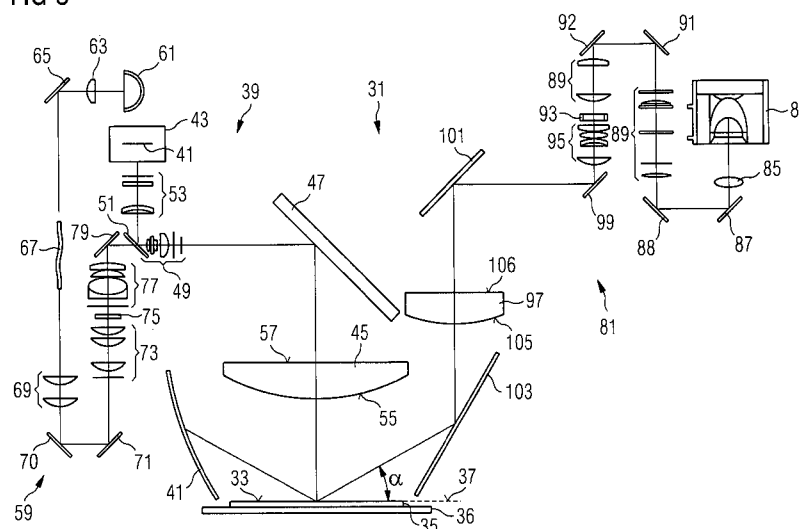
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(54) Title: OPTICAL INSPECTION SYSTEM AND METHOD

FIG 3



(57) Abstract: A wafer inspection system has a bright field imaging beam path and a dark field imaging beam path to obtain bright field images and dark field images of a full 300 mm wafer. The optical system provides for telecentric imaging and has low optical aberrations. The bright field and dark field beam paths are folded such that the system can be integrated to occupy a low volume with a small foot print.